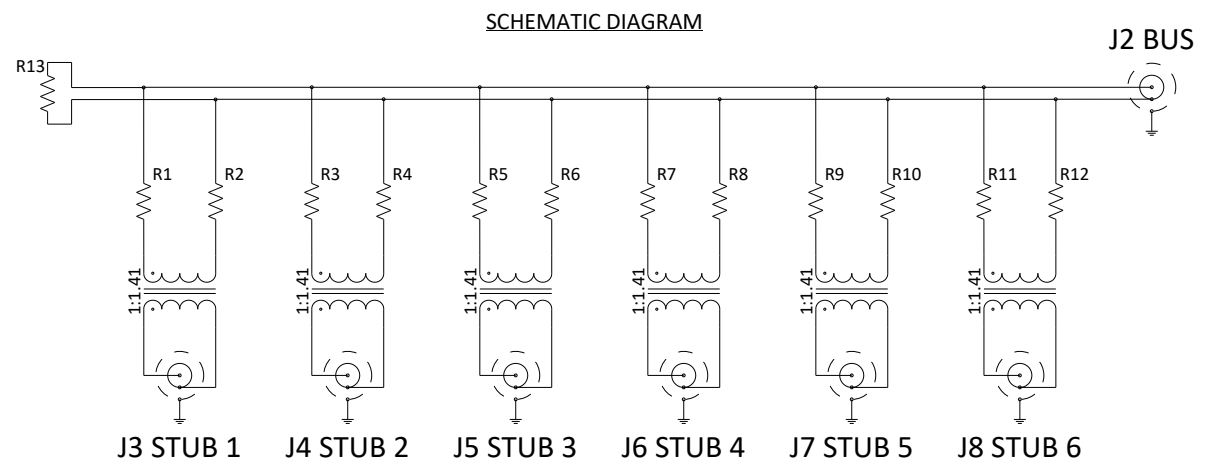


- 1.0 ELECTRICAL SPECIFICATIONS: IAW MIL-STD-1553B**
- 1.1 COMMON MODE REJECTION: -45.0 Db MAX @ 1.0MHz
 - 1.2 DROOP: 20% MAX (250kHz)
 - 1.3 OVERSHOOT & RINGING: $\pm 1.0V$ PEAK (250kHz SQUARE WAVE WITH 100Ns)
 - 1.4 STUB VOLTAGE: 1.0V TO 14.0V P-P; LINE TO LINE; SIGNAL VOLTAGE, TRANSFORMER COUPLING
- 4**
- 1.5 INPUT IMPEDANCE OF BUS: 3000 OHMS MIN. (75kHz - 1.0MHz), STUB WITH OPEN CIRCUIT
 - 1.6 CHARACTERISTIC IMPEDANCE: $Z_0=78$ OHMS
 - 1.7 FAULT PROTECTION: 59 OHMS $\pm 1\%$ 1W (R1-R12) IN SERIES WITH TRANSFORMER WINDING ON BUS SIDE
 - 1.8 TERMINATION RESISTOR VALUE: 78.7 OHMS $\pm 1\%$ 2W (R13) BUS TERMINATION



- 2.0 MECHANICAL SPECIFICATIONS:**
- 2.1 ENCLOSURE MATERIAL: AL 5754, 2MM THK. FINISH: CHEMICAL FILM PER SI-0000-0036, CLASS 2
 - 2.2 MOUNTING PLATE MATERIAL: AL 5754, 2MM THK. FINISH: CHEMICAL FILM PER SI-0000-0036, CLASS 2
- 5**
- 3.0 ENVIRONMENTAL SPECIFICATIONS:**
- 3.1 OPERATING TEMPERATURE RANGE: -55°C TO 125°C
 - 3.2 VIBRATION: MIL-STD-810G_CHG-1 METHOD 514.7 PROCEDURE I
 - 3.3 SHOCK: MIL-STD-810G_CHG-1 METHOD 516.7 PROCEDURE V
 - 3.4 HIGH TEMPERATURE OPERATING: MIL-STD-810G_CHG-1 METHOD 501.6 PROCEDURE II, +125°C
 - 3.5 LOW TEMPERATURE OPERATING: MIL-STD-810G_CHG-1 METHOD 502.6 PROCEDURE II, -55°C
 - 3.6 HIGH TEMPERATURE STORAGE: MIL-STD-810G_CHG-1 METHOD 501.6 PROCEDURE I, +125°C
 - 3.7 LOW TEMPERATURE STORAGE: MIL-STD-810G_CHG-1 METHOD 502.6 PROCEDURE I, -55°C
 - 3.8 RAIN: MIL-STD-810G METHOD 506.5 PROCEDURE I
- 6**

INTERMATEABILITY

| CONNECTOR | RECOMMENDED MATING CONNECTOR |
|-----------|------------------------------|
| BJ770 | PL75 |

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS.

| | | | | | |
|----------------------------------|-------|----------|---------------|-------|----------------------|
| PRODUCT NAME | | | | | www.delco.com.tr |
| BOX TYPE BUS COUPLER 6 STUB LTRM | | | | | |
| DOCUMENT NAME | | | | | SHEET |
| DE8226 - TECHNICAL DRAWING | | | | | |
| SIZE | SCALE | REVISION | REVISION DATE | SHEET | |
| A3 | 1:1 | 1 | 28.11.2023 | 1/1 | |

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